

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7476303

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YI-LIN CHUANG	07/10/2020
SHI-WEN TAN	07/10/2020
SONG LIU	07/10/2020
SHIH-YAO LIN	07/10/2020
WEN-YUAN FANG	07/10/2020

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD. 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
Name:	TSMC NANJING COMPANY LIMITED
Street Address:	16, ZIFENG ROAD, PUKOU ECONOMIC DEVELOPMENT ZONE
City:	NANJING, JIANGSU PROVINCE
State/Country:	CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17883246

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	T1516.10760US03
NAME OF SUBMITTER:	R. BURNS ISRAELSEN
SIGNATURE:	/R. Burns Israelsen, Reg. No. 42685/
DATE SIGNED:	08/09/2022
Total Attachments: 2 source=T1516-10760US03_Assignment#page1.tif source=T1516-10760US03_Assignment#page2.tif	

ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) _____
METHOD FOR OPTIMIZING FLOOR PLAN FOR AN INTEGRATED CIRCUIT

The PATENT RIGHTS referred to in this agreement are:

(check one) a patent application for this invention, executed by the ASSIGNOR(S)
 concurrently with this assignment.

U.S. patent application Serial No. 17/071,862, filed October 15, 2020

a U.S. patent application based on PCT International Application

No. _____ filed on (date) _____ (U.S. patent application
 Serial No. _____, if known).

U.S. patent No. _____, issued _____.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of
 the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

U.S. patent rights only.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures
 appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) 1.TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.

2.TSMC Nanjing Company Limited

(Address) 1.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan, R.O.C.

2.16, Zifeng Road, Pukou Economic Development Zone, Nanjing, Jiangsu

Province, China

The ASSIGNEE is:

(check one) An individual.

A Partnership.

A Corporation of 1.TAIWAN, R.O.C.
2.CHINA, P.R.C. (specify state or country)

(other) _____

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and
 valuable consideration, receipt of which is acknowledged, hereby assign(s) the following
 rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable
 provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO
ASSIGNEE: 1.TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
2.TSMC Nanjing Company Limited
INVENTION TITLE: METHOD FOR OPTIMIZING FLOOR PLAN FOR AN
INTEGRATED CIRCUIT

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Yi-Lin CHUANG *Yi-Lin Chuang* 2020.7.10
Name of sole or first inventor Signature Date

Shi-Wen TAN *Shi-Wen Tan* 2020.7.10
Name of second inventor, if any Signature Date

Song LIU *Liu Song* 07/10/2020
Name of third inventor, if any Signature Date

Shih-Yao LIN *Shih-Yao Lin* 2020.7.10
Name of fourth inventor, if any Signature Date

Wen-Yuan FANG *Wen-Yuan FANG* 2020.7.10
Name of fifth inventor, if any Signature Date

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